

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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SMD Schottky Diode

FEATURES

- Epitaxial planar die construction
- Surface device type mounting
- Moisture sensitivity level 1
- Matte Tin(Sn) lead finish with Nickel(Ni) underplate
- Packing code with suffix "G" means green compound (halogen-free)





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MECHANICAL DATA

- Case: SOT- 23, molded plastic

- Terminal: Matte tin plated, lead free, solderable per MIL-STD-202, Method 208 guaranteed

- High temperature soldering guaranteed: 260°C/10s

- Weight: 0.008g (approximately)

- Marking Code: D3Q

MAXIMUM RATINGS AND ELECTRICAL CHARACTERSTICS (T _A =25°C unless otherwise noted)				
PARAMETER	SYMBOL	VALUE	UNIT	
Power Dissipation	P _D	200	mW	
Repetitive Peak Reverse Voltage	V_{RRM}	40	V	
Reverse Voltage	V _R	25	V	
Mean Forward Current	I _O	350	mA	
Non-Repetitive Peak Forward Surge Current (Note 1)	I _{FSM}	1.5	А	
Junction and Storage Temperature Range	T_J, T_{STG}	-40 to +125	°C	

PARAM	SYMBOL	MIN	MAX	UNIT	
Reverse Breakdown Voltage	I _R =100μA	$V_{(BR)}$	40	-	V
Forward Voltage	I _F =10mA	V _F	-	0.32	V
Forward Voltage	I _F =200mA	■ V _F	-	0.55]
Reverse Leakage Current V _R =25V		I _R	-	70	μΑ
Junction Capacitance V _R =0V, f=1.0MHz		CJ	-	50	pF

Note 1: Mean output current per element : I_O/2



RATINGS AND CHARACTERISTICS CURVES

(T_A=25°C unless otherwise noted)

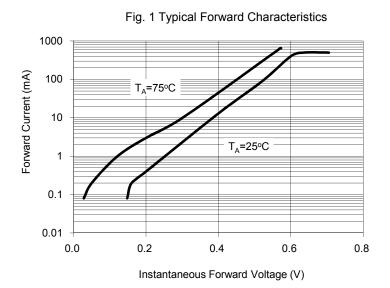
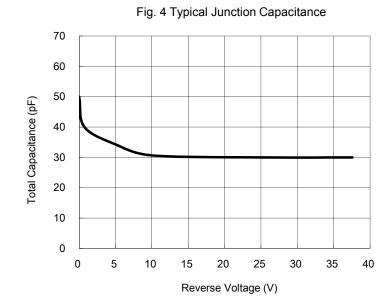


Fig. 2 Reverse Current VS. Reverse Voltage 1000 T_A=75°C 100 Reverse Current (nA) T_A=25°C 10 0.1 0 10 20 100 30 40 50 60 70 80 90 Reverse Voltage (V)

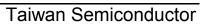
Fig. 3 Admissible Power Dissipation Curve

250
200
150
150
0
0
25 50 75 100 125 150

Ambient Temperature (°C)



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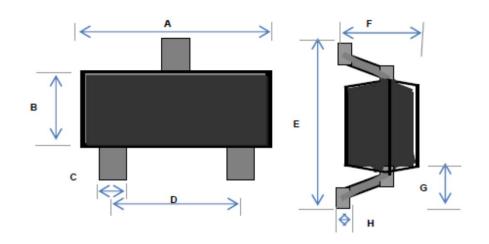
ORDERIN	ORDERING INFORMATION				
PART NO.	PART NO. SUFFIX (Note 1)	PACKING CODE	PACKING CODE SUFFIX	PACKAGE	PACKING
RB495D	-xx	RF R5	G	SOT-23	3K / 7" Reel 10K / 13" Reel

Note 1: Part No. Suffix "-xx " would be used for special requirement

EXAMPLE					
PREFERRED P/N	PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION
RB495D RF	RB495D		RF		Multiple manufacture source
RB495D RFG	RB495D		RF	G	Multiple manufacture source Green compound
RB495D-D0 RFG	RB495D	-D0	RF	G	Defined manufacture source Green compound
RB495D-B0 R5G	RB495D	-B0	R5	G	Defined manufacture source Green compound

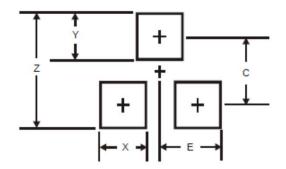


PACKAGE OUTLINE DIMENSIONS



DIM.	Unit(mm)		Unit(inch)	
DIIVI.	Min	Max	Min	Max
Α	2.70	3.10	0.106	0.122
В	1.10	1.50	0.043	0.059
С	0.30	0.51	0.012	0.020
D	1.78	2.04	0.070	0.080
Е	2.10	2.64	0.083	0.104
F	0.89	1.30	0.035	0.051
G	0.55 REF		0.022	REF
Н	0.10 REF		0.004 REF	

SUGGEST PAD LAYOUT



DIM.	Unit(mm)	Unit(inch)		
DIIVI.	Тур.	Тур.		
Z	2.8	0.110		
Х	0.7	0.028		
Υ	0.9	0.035		
С	1.9	0.075		
Е	1.0	0.039		





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